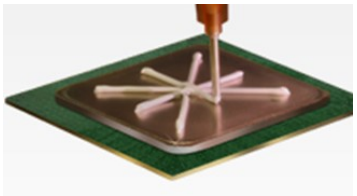
G751 (Non-Solvent) TECHNICAL DATA SHEET

Product description

Thermal grease, G751, is a Non-Solvent thermal interface material developed and manufactured by Shin-Etsu Chemical Co., Ltd. Shin-Etsu MicroSi's G751 exceeds thermal management requirements of high-performance semiconductor devices. Through superior heat dissipation, the G751 allows electronic devices to remain cooler and increases their long term reliability. Typical applications include semiconductor devices: power transistors, ICs, CPUs, stacked memory modules or any application that requires a thermal solution.

Product characteristics

- Excellent thermal resistance (TR) and thermal conductivity (TC)
- Easily applied via dispensing, stencil printing, or screen printing methods
- Stable homogeneous mixture for consistent thermal performance
- RoHS and REACH Compliant
- High volume production product from a proven industry leader
- Available worldwide through established supply chain networks



Packages

SEM's G751 material is available in several cost effective packages offering unique advantages:

- **Syringes** offer most flexibility, with the ability to utilize the same product package for production and field requirements

Packaging Description	G751
Syringes	0.5 gm, 1.0 gm
Cartridges	55 gm
Bulk	1 kg can
Custom Sizes Available	
Storage Conditions	32°F to 85°F

- **Cartridges** can be utilized with either manual, automated or silk-screening equipment. The delivery system allows dispensing of the material, while protecting the integrity and exposure level of the unused portion.
- **Bulk** purchases with the lowest unit cost, are available for large scale production facilities where material is consumed at a rapid rate.

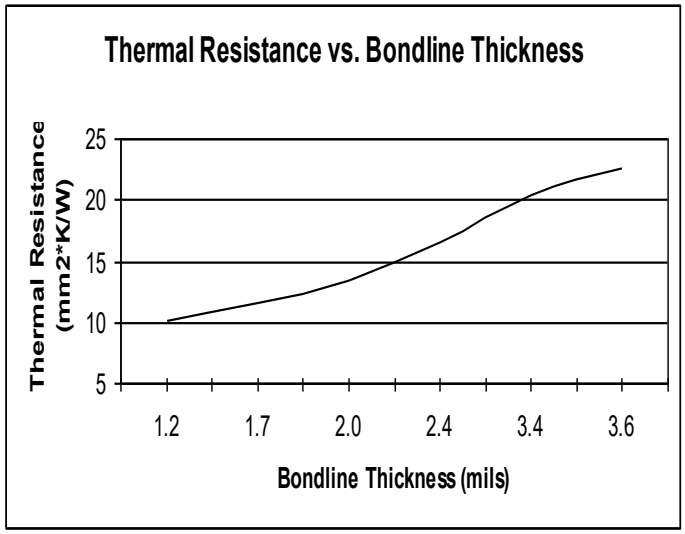
General properties

Attributes	Typical Values
Color	Grey
Viscosity @25°C(mPa·s)	400
Specific Gravity	2.5
Thermal Conductivity * (W/m °K)	4.7
Thermal Resistance ** mm^2·K/W	17.0
Bond Line Thickness (um) @20psi	73

*Measured with hot disc method ** Measured with laser-flash Method

G751

A key factor in selecting a thermal interface material is the relationship between bond line thickness (BLT) and thermal resistance. The chart on the left illustrates very low thermal resistance at different bond line thicknesses.



The viscosity of G-751 allows for consistent dispense patterns when utilizing stencil printing or automated dispense machines. This advantage allows for tighter control in the use of and dispensing of the thermal interface material

"**WARNING:** This product can expose you to chemicals including Lead, which is known to the State of California to cause cancer and birth defects or other reproductive harm. For more information go to www.P65Warnings.ca.gov."

Caution

Shin-Etsu MicroSi (SEM) has been notified by customers that they were negatively impacted by using unauthorized and/or counterfeit thermal interface materials being sold as Shin-Etsu materials. Please note that Shin-Etsu Chemical Co., Ltd. And SEM, Inc. are not in a position to take any responsibility for the said unauthorized materials. Feel free to contact SEM, if you have any questions regarding this.

To ensure safety, follow the precautions stated in the material safety data sheet and technical references.

Typical values of different parameters have been shared in this sheet. It's the responsibility of the Purchasers to qualify the products for their respective applications. The contents in this document are subject to revision without notice to reflect latest data.
Permission is required to reprint our data.

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